



# Product Change Notification

## 109500 - 00

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Should you have any issues with the timeline or content of this change, please contact the Intel Representative(s) for your geographic location listed below. No response from customers will be deemed as acceptance of the change and the change will be implemented pursuant to the key milestones set forth in this attached PCN.

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**Asia Pacific Contact:** <mailto:apacgccb@intel.com>

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# Product Change Notification

**Change Notification#:** 109500 - 00

**Change Title:** Intel(R) Hot-swap Backplane  
FXX6DRV3GEXPBRD, PCN 109500-00,  
Product Material, Add Mylar around the PCB  
mounting hole

**Date of Publication:** December 22, 2009

## Key Characteristics of the Change:

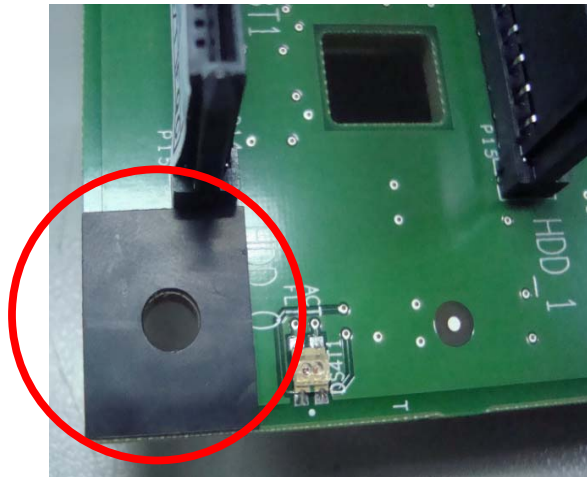
Product Material

## Forecasted Key Milestones:

Date Customer Must be Ready to Receive Post-Conversion Material:	Jan 22, 2009
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## Description of Change to the Customer:

Intel factory will add Mylar on the backplane PCB (Printed Circuit Board), around the mounting hole near HDD (Hard Disk Drive) slot 0 in order to increase mechanical separation and electrical insulation. Please refer to the following photo for the Mylar pad location.



## Customer Impact of Change and Recommended Action:

Intel anticipates no impact to customers.

## Products Affected / Intel Ordering Codes:

Pre Change Product Code	Pre Change MM#	Pre Change TA	Pre Change PBA	Post Change MM#	Post Change TA	Post Change PBA
FXX6DRV3GEXPBRD	879632	D72612-201	D22809-203	879632	D72612-202	D22809-204

**Reference Documents / Attachments:**

**Document:**

**Location #:**

**PCN Revision History:**

**Date of Revision:**

**Revision Number:**

**Reason:**

December 22, 2009

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Originally Published PCN